



# EcoClean

## Flexible Plasma Resist Strip/Descum System with Low CoO

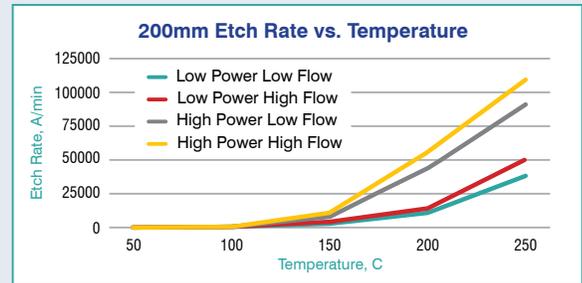


- High strip rate and high throughput
- Small footprint with single chamber
- No defects or damage due to ICP downstream plasma
- R&D to high volume production with minimal downtime
- Eco-friendly “green” process

Highly Controlled Removal Rate  
 100 to 100,000 Å/min  
 Up to 65 wph process  
 2-5x faster,  
 ½ the capital cost

Creating advanced solutions for present and next-generation technologies, the EcoClean system offers engineers flexibility and reliability for wafers:

- Photoresist removal
- PR descum
- Polyimide removal
- Organics removal
- Copper oxide removal



MEMS  
 LED  
 MicroLED  
 Advanced Packaging  
 Power Devices  
 Sensors

Yield Engineering Systems (YES) has designed the EcoClean as a high throughput, low-cost of ownership, single-wafer photoresist removal system. The ICP remote source generates atomic oxygen which chemically reacts with the photoresist of the wafer surface. By employing a downstream resist strip process, high removal rate is achieved with no electrical damage or defects to the substrates and devices. EcoClean offers automated processing with low gas usage and is an eco-friendly “green” solution.

**Contact Us:** We offer process demonstrations. If you would like to submit samples, please call us. We can run your samples and provide a detailed process report.

**Yield Engineering Systems, Inc.**

Call: **1-510-954-6889** (worldwide) or **1-888-YES-3637** (US toll free)

[www.yieldengineering.com](http://www.yieldengineering.com)



# EcoClean

## SPECIFICATIONS

	SPECIFICATIONS	REMARKS	
PERFORMANCE	<b>Descum Specifications</b>		
	Approx. Ash Rate	100-1000 Å/min	
	Uniformity	Within wafer: $\leq \pm 10\%$	
	<b>Photoresist Strip Rate</b>		
	Strip Rate	$\geq 5 \mu\text{m}/\text{min}$	Temperature and photo resist dependent $\geq 10 \mu\text{m}/\text{min}$ @250C
	Uniformity	Within wafer: $\leq \pm 10\%$	
HARDWARE	<b>Wafer Per Month</b>	At least $\geq 20\text{K}$ / month	The process time including load and unload
	Wafer Temperature Range	75° to 300° C	
	WiW temp Uniformity	$\pm 1.5\%$	5 point TC wafer measured at 200° C
	Capacity	Single wafer/50mm-150mm	Capable of up to 200mm wafer
	Process Gas Inputs	2 MFCs standard (Oxygen and Nitrogen), 3rd forming gas MFC optional	
	O2 MFC	2000 sccm	
	N2 MFC	200 sccm	
	Base Pressure	$\leq 50$ mTorr	With 350cfm Ebara Dry Pump (EV-S100)
	Leak Rate	$\leq 20$ mTorr/min	
	RF Power	500W - 3000W	
	SOFTWARE	User Interface	PC with touch screen monitor and pull-out keyboard, barcode reader
SECS/GEM		Optional	
Operating System		Windows 10 Currently supports wired Ethernet communication	

**Yield Engineering Systems, Inc.**

Call: **1-510-954-6889** (worldwide) or **1-888-YES-3637** (US toll free)

[www.yieldengineering.com](http://www.yieldengineering.com)